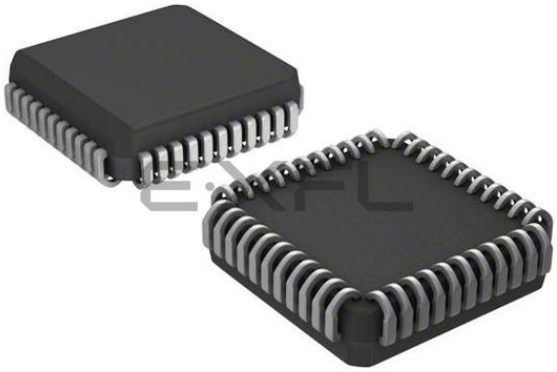

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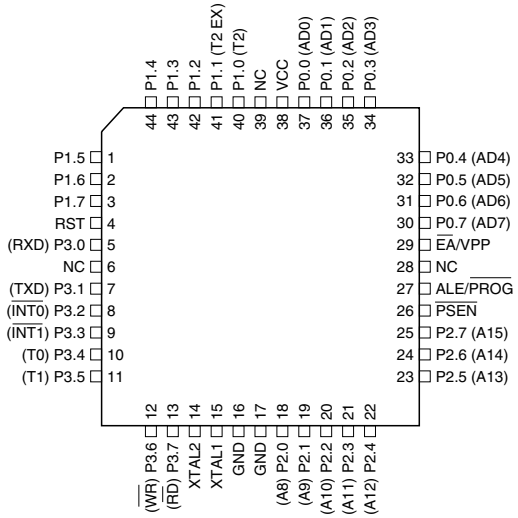
Applications of "Embedded - Microcontrollers"

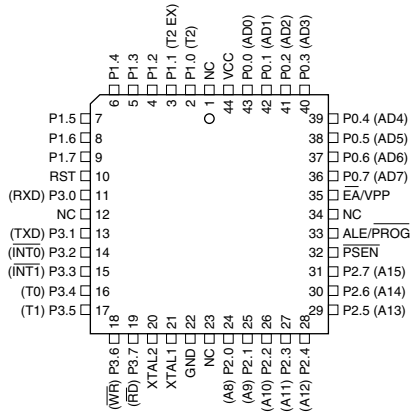
Details	
Product Status	Active
Core Processor	8051
Core Size	8-Bit
Speed	24MHz
Connectivity	SPI, UART/USART
Peripherals	WDT
Number of I/O	32
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	512 x 8
Voltage - Supply (Vcc/Vdd)	4V ~ 5.5V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-LCC (J-Lead)
Supplier Device Package	44-PLCC (16.6x16.6)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/at89c51rc-24ju

2. Pin Configurations

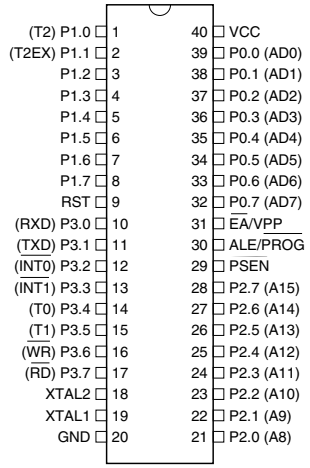
2.1 44A – 44-lead TQFP



2.2 44J – 44-lead PLCC



2.3 40P6 – 40-lead PDIP



Note that not all of the addresses are occupied, and unoccupied addresses may not be implemented on the chip. Read accesses to these addresses will in general return random data, and write accesses will have an indeterminate effect.

User software should not write 1s to these unlisted locations, since they may be used in future products to invoke new features. In that case, the reset or inactive values of the new bits will always be 0.

Timer 2 Registers: Control and status bits are contained in registers T2CON (shown in Table 5-2) and T2MOD (shown in Table 13-1 and Table 5-4) for Timer 2. The register pair (RCAP2H, RCAP2L) are the Capture/Reload registers for Timer 2 in 16-bit capture mode or 16-bit auto-reload mode.

Interrupt Registers: The individual interrupt enable bits are in the IE register. Two priorities can be set for each of the six interrupt sources in the IP register.

Dual Data Pointer Registers: To facilitate accessing both internal and external data memory, two banks of 16-bit Data Pointer Registers are provided: DP0 at SFR address locations 82H-83H and DP1 at 84H-85H. Bit DPS = 0 in SFR AUXR1 selects DP0 and DPS = 1 selects DP1. The user should always initialize the DPS bit to the appropriate value before accessing the respective Data Pointer Register.

Power Off Flag: The Power Off Flag (POF) is located at bit 4 (PCON.4) in the PCON SFR. POF is set to “1” during power up. It can be set and reset under software control and is not affected by reset.

Table 5-3. AUXR: Auxiliary Register

AUXR — Address = 8EH — Reset Value = XXX00X00B

Not Bit Addressable

	–	–	–	WDIDLE	DISRTO	–	EXTRAM	DISALE
Bit	7	6	5	4	3	2	1	0

–	Reserved for future expansion	
DISALE	Disable/Enable ALE	
	DISALE	Operating Mode
	0	ALE is emitted at a constant rate of 1/6 the oscillator frequency
	1	ALE is active only during a MOVX or MOVC instruction
EXTRAM	Internal/External RAM access using MOVX @ Ri/@DPTR	
	EXTRAM	Operating Mode
	0	Internal ERAM (00H-FFH) access using MOVX @ Ri/@DPTR
	1	External data memory access
DISRTO	Disable/Enable Reset out	
	DISRTO	Operating Mode
	0	Reset pin is driven High after WDT times out
	1	Reset pin is input only
WDIDLE	Disable/Enable WDT in IDLE mode	
	WDIDLE	Operating Mode
	0	WDT continues to count in IDLE mode
	1	WDT halts counting in IDLE mode

Table 5-4. AUXR1: Auxiliary Register 1

AUXR1 — Address = A2H — Reset Value = XXXXXXX0B

Not Bit Addressable

	–	–	–	–	–	–	–	DPS
Bit	7	6	5	4	3	2	1	0

–	Reserved for future expansion	
DPS	Data Pointer Register Select	
	DPS	
	0	Selects DPTR Registers DP0L, DP0H
	1	Selects DPTR Registers DP1L, DP1H

6. Memory Organization

The MCS-51 devices have a separate address space for Program and Data Memory. Up to 64K bytes each of external Program and Data Memory can be addressed.

7. Program Memory

If the $\overline{EA}$ pin is connected to GND, all program fetches are directed to external memory.

On the AT89C51RC, if $\overline{EA}$ is connected to V_{CC}, program fetches to addresses 0000H through 7FFFH are directed to internal memory and fetches to addresses 8000H through FFFFH are to external memory.

7.1 Data Memory

The AT89C51RC has internal data memory that is mapped into four separate segments: the lower 128 bytes of RAM, upper 128 bytes of RAM, 128 bytes special function register (SFR) and 256 bytes expanded RAM (ERAM).

The four segments are:

1. The Lower 128 bytes of RAM (addresses 00H to 7FH) are directly and indirectly addressable.
2. The Upper 128 bytes of RAM (addresses 80H to FFH) are indirectly addressable only.
3. The Special Function Registers, SFRs, (addresses 80H to FFH) are directly addressable only.
4. The 256-byte expanded RAM (ERAM, 00H-FFH) is indirectly accessed by MOVX instructions, and with the EXTRAM bit cleared.

The Lower 128 bytes can be accessed by either direct or indirect addressing. The Upper 128 bytes can be accessed by indirect addressing only. The Upper 128 bytes occupy the same address space as the SFR. This means they have the same address, but are physically separate from the SFR space.

When an instruction accesses an internal location above address 7FH, the CPU knows whether the access is to the upper 128 bytes of data RAM or to SFR space by the addressing mode used in the instruction. Instructions that use direct addressing access SFR space. For example:

```
MOV 0A0H, # data
```

accesses the SFR at location 0S0H (which is P2). Instructions that use indirect addressing access the Upper 128 bytes of data RAM. For example:

```
MOV@R0, # data
```

where R0 contains 0A0H, accesses the data byte at address 0A0H, rather than P2 (whose address is 0A0H).

Note that stack operations are examples of indirect addressing, so the upper 128 bytes of data RAM are available as stack space.

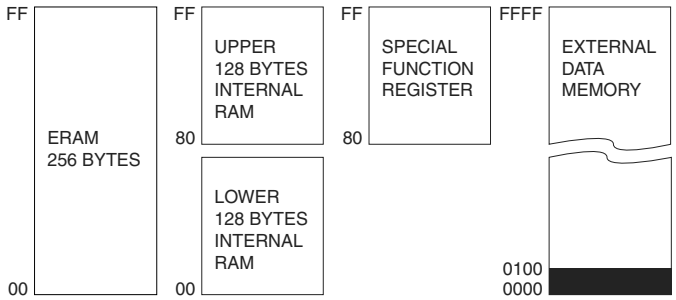
The 256 bytes of ERAM can be accessed by indirect addressing, with EXTRAM bit cleared and MOVX instructions. This part of memory is physically located on-chip, logically occupying the first 256 bytes of external data memory.

With EXTRAM = 0, the ERAM is indirectly addressed, using the MOVX instruction in combination with any of the registers R0, R1 of the selected bank or DPTR. An access to ERAM will not affect ports P0, P2, P3.6 ($\overline{WR}$), and P3.7 ($\overline{RD}$). For example, with EXTRAM = 0,

```
MOVX@R0, # data
```

where R0 contains 0A0H, accesses the ERAM at address 0A0H rather than external memory. An access to external data memory locations higher than FFH (i.e. 0100H to FFFFH) will be performed with the MOVX DPTR instructions in the same way as in the standard 80C51, i.e., with P0 and P2 as data/address bus, and P3.6 and P3.7 as write and read timing signals (see Figure 7-1).

Figure 7-1. Internal and External Data Memory Address (with EXTRAM = 0)



With EXTRAM = 1, MOVX @ Ri and MOVX@DPTR will be similar to the standard 80C51. MOVX@Ri will provide an 8-bit address multiplexed with data on Port 0 and any output port pins can be used to output higher-order address bits. This is to provide the external paging capability. MOVX@DPTR will generate a 16-bit address. Port 2 outputs the high-order 8 address bits (the contents of DP0H), while Port 0 multiplexes the low-order 8 address bits (the contents of DP0L) with data. MOVX@Ri and MOVX@DPTR will generate either read or write signals on P3.6 ($\overline{WR}$) and P3.7 ($\overline{RD}$).

The stack pointer (SP) may be located anywhere in the 256 bytes RAM (lower and upper RAM) internal data memory. The stack may not be located in the ERAM.

8. Hardware Watchdog Timer (One-time Enabled with Reset-out)

The WDT is intended as a recovery method in situations where the CPU may be subjected to software upsets. The WDT consists of a 13-bit counter and the WatchDog Timer Reset (WDTRST) SFR. The WDT is defaulted to disable from exiting reset. To enable the WDT, a user must write 01EH and 0E1H in sequence to the WDTRST register (SFR location 0A6H). When the WDT is enabled, it will increment every machine cycle while the oscillator is running. The WDT timeout period is dependent on the external clock frequency. There is no way to disable the WDT except through reset (either hardware reset or WDT overflow reset). When WDT overflows, it will drive an output RESET HIGH pulse at the RST pin.

9. Using the WDT

To enable the WDT, a user must write 01EH and 0E1H in sequence to the WDTRST register (SFR location 0A6H). When the WDT is enabled, the user needs to service it by writing 01EH and 0E1H to WDTRST to avoid a WDT overflow. The 13-bit counter overflows when it reaches 8191 (1FFFH), and this will reset the device. When the WDT is enabled, it will increment every machine cycle while the oscillator is running. This means the user must re-initialize the WDT at least every 8191 machine cycles. To re-initialize the WDT the user must write 01EH and 0E1H to WDTRST. WDTRST is a write-only register. The WDT counter cannot be read or written. When WDT overflows, it will generate an output RESET pulse at the RST pin. The RESET pulse duration is 98xTOSC, where TOSC=1/FOSC. To make the best use of the WDT, it should be serviced in those sections of code that will periodically be executed within the time required to prevent a WDT reset.

10. WDT During Power-down and Idle

In Power-down mode the oscillator stops, which means the WDT also stops. While in Power-down mode, the user does not need to service the WDT. There are two methods of exiting Power-down mode: by a hardware reset or via a level-activated external interrupt which is enabled prior to entering Power-down mode. When Power-down is exited with hardware reset, servicing the WDT should occur as it normally does whenever the AT89C51RC is reset. Exiting Power-down with an interrupt is significantly different. The interrupt is held low long enough for the oscillator to stabilize. When the interrupt is brought high, the interrupt is serviced. To prevent the WDT from resetting the device while the interrupt pin is held low, the WDT is not started until the interrupt is pulled high. It is suggested that the WDT be reset during the interrupt service for the interrupt used to exit Power-down mode.

To ensure that the WDT does not overflow within a few states of exiting Power-down, it is best to reset the WDT just before entering Power-down mode.

Before going into the IDLE mode, the WDIDLE bit in SFR AUXR is used to determine whether the WDT continues to count if enabled. The WDT keeps counting during IDLE (WDIDLE bit = 0) as the default state. To prevent the WDT from resetting the AT89C51RC while in IDLE mode, the user should always set up a timer that will periodically exit IDLE, service the WDT, and reenter IDLE mode.

With WDIDLE bit enabled, the WDT will stop to count in IDLE mode and resumes the count upon exit from IDLE.

11. UART

The UART in the AT89C51RC operates the same way as the UART in the AT89C51 and AT89C52. For more detailed information on the UART operation, please click on the document link below:

http://www.atmel.com/dyn/resources/prod_documents/DOC4316.PDF

14. Baud Rate Generator

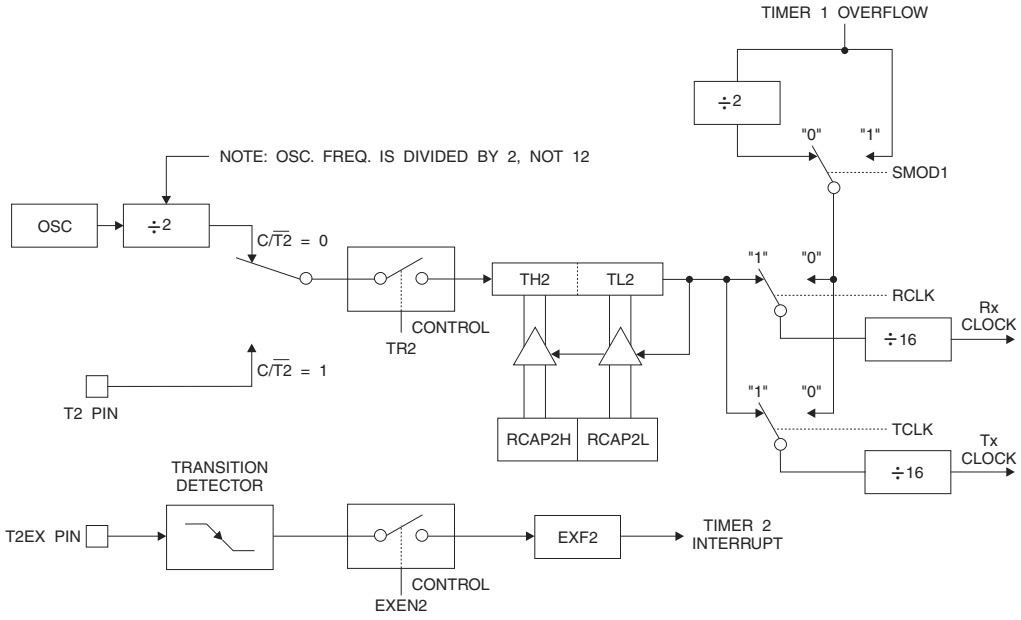
Timer 2 is selected as the baud rate generator by setting TCLK and/or RCLK in T2CON (Table 5-2). Note that the baud rates for transmit and receive can be different if Timer 2 is used for the receiver or transmitter and Timer 1 is used for the other function. Setting RCLK and/or TCLK puts Timer 2 into its baud rate generator mode, as shown in Figure 14-1.

The baud rate generator mode is similar to the auto-reload mode, in that a rollover in TH2 causes the Timer 2 registers to be reloaded with the 16-bit value in registers RCAP2H and RCAP2L, which are preset by software.

The baud rates in Modes 1 and 3 are determined by Timer 2's overflow rate according to the following equation.

$$\text{Mdes 1 and 3 Baud Rates} = \frac{\text{Timer 2 Overflow Rate}}{16}$$

Figure 14-1. Timer 2 in Baud Rate Generator Mode



The Timer can be configured for either timer or counter operation. In most applications, it is configured for timer operation (CP/$\overline{T2}$ = 0). The timer operation is different for Timer 2 when it is used as a baud rate generator. Normally, as a timer, it increments every machine cycle (at 1/12 the oscillator frequency). As a baud rate generator, however, it increments every state time (at 1/2 the oscillator frequency). The baud rate formula is given below.

$$\frac{\text{Modes 1 and 3}}{\text{Baud Rate}} = \frac{\text{Oscillator Frequency}}{32 \times [65536\text{-RCAP2H,RCAP2L})]}$$

where (RCAP2H, RCAP2L) is the content of RCAP2H and RCAP2L taken as a 16-bit unsigned integer.

Timer 2 as a baud rate generator is shown in Figure 14-1. This figure is valid only if RCLK or TCLK = 1 in T2CON. Note that a rollover in TH2 does not set TF2 and will not generate an inter-

rupt. Note too, that if EXEN2 is set, a 1-to-0 transition in T2EX will set EXF2 but will not cause a reload from (RCAP2H, RCAP2L) to (TH2, TL2). Thus when Timer 2 is in use as a baud rate generator, T2EX can be used as an extra external interrupt.

Note that when Timer 2 is running (TR2 = 1) as a timer in the baud rate generator mode, TH2 or TL2 should not be read from or written to. Under these conditions, the Timer is incremented every state time, and the results of a read or write may not be accurate. The RCAP2 registers may be read but should not be written to, because a write might overlap a reload and cause write and/or reload errors. The timer should be turned off (clear TR2) before accessing the Timer 2 or RCAP2 registers.

15. Programmable Clock Out

A 50% duty cycle clock can be programmed to come out on P1.0, as shown in Figure 15-1. This pin, besides being a regular I/O pin, has two alternate functions. It can be programmed to input the external clock for Timer/Counter 2 or to output a 50% duty cycle clock ranging from 61 Hz to 4 MHz at a 16 MHz operating frequency.

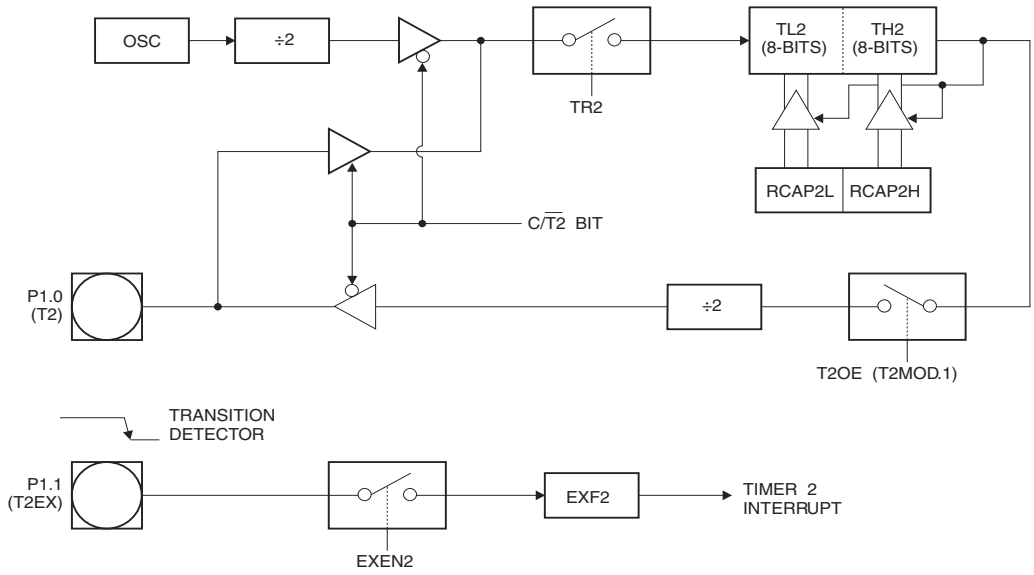
To configure the Timer/Counter 2 as a clock generator, bit C/$\overline{T2}$ (T2CON.1) must be cleared and bit T2OE (T2MOD.1) must be set. Bit TR2 (T2CON.2) starts and stops the timer.

The clock-out frequency depends on the oscillator frequency and the reload value of Timer 2 capture registers (RCAP2H, RCAP2L), as shown in the following equation.

$$\text{Clock-Out Frequency} = \frac{\text{Oscillator Frequency}}{4 \times [65536-(\text{RCAP2H,RCAP2L})]}$$

In the clock-out mode, Timer 2 roll-overs will not generate an interrupt. This behavior is similar to when Timer 2 is used as a baud-rate generator. It is possible to use Timer 2 as a baud-rate generator and a clock generator simultaneously. Note, however, that the baud-rate and clock-out frequencies cannot be determined independently from one another since they both use RCAP2H and RCAP2L.

Figure 15-1. Timer 2 in Clock-Out Mode



16. Interrupts

The AT89C51RC has a total of six interrupt vectors: two external interrupts ($\overline{INT0}$ and $\overline{INT1}$), three timer interrupts (Timers 0, 1, and 2), and the serial port interrupt. These interrupts are all shown in Figure 16-1.

Each of these interrupt sources can be individually enabled or disabled by setting or clearing a bit in Special Function Register IE. IE also contains a global disable bit, EA, which disables all interrupts at once.

Note that Table 14-1 shows that bit position IE.6 is unimplemented. User software should not write 1s to these bit positions, since they may be used in future AT89 products.

Timer 2 interrupt is generated by the logical OR of bits TF2 and EXF2 in register T2CON. Neither of these flags is cleared by hardware when the service routine is vectored to. In fact, the service routine may have to determine whether it was TF2 or EXF2 that generated the interrupt, and that bit will have to be cleared in software.

The Timer 0 and Timer 1 flags, TF0 and TF1, are set at S5P2 of the cycle in which the timers overflow. The values are then polled by the circuitry in the next cycle. However, the Timer 2 flag, TF2, is set at S2P2 and is polled in the same cycle in which the timer overflows.

Table 16-1. Interrupt Enable (IE) Register

(MSB) (LSB)

EA	–	ET2	ES	ET1	EX1	ET0	EX0

Enable Bit = 1 enables the interrupt.

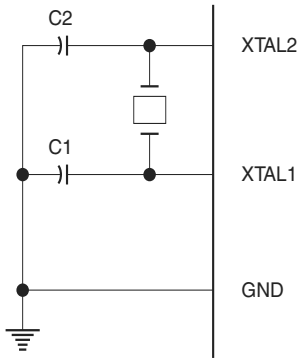
Enable Bit = 0 disables the interrupt.

Symbol	Position	Function
EA	IE.7	Disables all interrupts. If EA = 0, no interrupt is acknowledged. If EA = 1, each interrupt source is individually enabled or disabled by setting or clearing its enable bit.
–	IE.6	Reserved.
ET2	IE.5	Timer 2 interrupt enable bit.
ES	IE.4	Serial Port interrupt enable bit.
ET1	IE.3	Timer 1 interrupt enable bit.
EX1	IE.2	External interrupt 1 enable bit.
ET0	IE.1	Timer 0 interrupt enable bit.
EX0	IE.0	External interrupt 0 enable bit.
User software should never write 1s to reserved bits, because they may be used in future AT89 products.		

19. Power-down Mode

In the Power-down mode, the oscillator is stopped, and the instruction that invokes Power-down is the last instruction executed. The on-chip RAM and Special Function Registers retain their values until the Power-down mode is terminated. Exit from Power-down can be initiated either by a hardware reset or by an enabled external interrupt. Reset redefines the SFRs but does not change the on-chip RAM. The reset should not be activated before V_{CC} is restored to its normal operating level and must be held active long enough to allow the oscillator to restart and stabilize.

Figure 19-1. Oscillator Connections



Note: C1, C2 = 30 pF ± 10 pF for Crystals
= 40 pF ± 10 pF for Ceramic Resonators

Figure 19-2. External Clock Drive Configuration

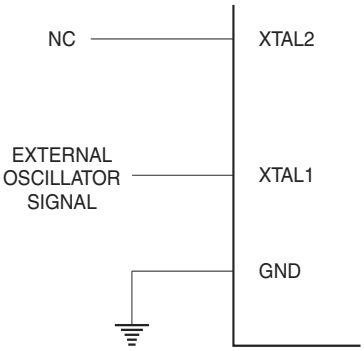


Table 19-1. Status of External Pins During Idle and Power-down Modes

Mode	Program Memory	ALE	$\overline{\text{PSEN}}$	PORT0	PORT1	PORT2	PORT3
Idle	Internal	1	1	Data	Data	Data	Data
Idle	External	1	1	Float	Data	Address	Data
Power-down	Internal	0	0	Data	Data	Data	Data
Power-down	External	0	0	Float	Data	Data	Data

Chip Erase Sequence: Before the AT89C51RC can be reprogrammed, a Chip Erase operation needs to be performed. To erase the contents of the AT89C51RC, follow this sequence:

1. Raise V_{CC} to 6.5V.
2. Pulse ALE/$\overline{\text{PROG}}$ once (duration of 200 ns - 500 ns) and wait for 150 ms.
3. Power V_{CC} down and up to 6.5V.
4. Pulse ALE/$\overline{\text{PROG}}$ once (duration of 200 ns - 500 ns) and wait for 150 ms.
5. Power V_{CC} down and up.

$\overline{\text{Data}}$ Polling: The AT89C51RC features $\overline{\text{Data}}$ Polling to indicate the end of a write cycle. During a write cycle, an attempted read of the last byte written will result in the complement of the written data on P0.7. Once the write cycle has been completed, true data is valid on all outputs, and the next cycle may begin. $\overline{\text{Data}}$ Polling may begin any time after a write cycle has been initiated.

Ready/$\overline{\text{Busy}}$: The progress of byte programming can also be monitored by the RDY/$\overline{\text{BSY}}$ output signal. P3.0 is pulled low after ALE goes high during programming to indicate $\overline{\text{BUSY}}$. P3.0 is pulled high again when programming is done to indicate READY.

Program Verify: If lock bits LB1 and LB2 have not been programmed, the programmed code data can be read back via the address and data lines for verification. The status of the individual lock bits can be verified directly by reading them back.

Reading the Signature Bytes: The signature bytes are read by the same procedure as a normal verification of locations 000H, 100H, and 200H, except that P3.6 and P3.7 must be pulled to a logic low. The values returned are as follows:

(000H) = 1EH indicates manufactured by Atmel
(100H) = 51H
(200H) = 07H indicates 89C51RC

22. Programming Interface

Every code byte in the Flash array can be programmed by using the appropriate combination of control signals. The write operation cycle is self-timed and once initiated, will automatically time itself to completion.

Most major worldwide programming vendors offer support for the Atmel AT89 microcontroller series. Please contact your local programming vendor for the appropriate software revision.

Table 22-1. Flash Programming Modes

Mode	V_{CC}	RST	$\overline{PSEN}$	ALE/ $\overline{PROG}$	$\overline{EA}$/ V_{PP}	P2.6	P2.7	P3.3	P3.6	P3.7	P0.7-0 Data	P3.4	P2.5-0	P1.7-0
												Address		
Write Code Data	5V	H	L	(1)	12 V	L	H	H	H	H	D_{IN}	A14	A13-8	A7-0
Read Code Data	5V	H	L	H	H/12 V	L	L	L	H	H	D_{OUT}	A14	A13-8	A7-0
Write Lock Bit 1	6.5V	H	L	(2)	12 V	H	H	H	H	H	X	X	X	X
Write Lock Bit 2	6.5V	H	L	(2)	12 V	H	H	H	L	L	X	X	X	X
Write Lock Bit 3	6.5V	H	L	(2)	12 V	H	L	H	H	L	X	X	X	X
Read Lock Bits 1, 2, 3	5V	H	L	H	H	H	H	L	H	L	P0.2, P0.3, P0.4	X	X	X
Chip Erase	6.5V	H	L	(3)	12V	H	L	H	L	L	X	X	X	X
Read Atmel ID	5V	H	L	H	H	L	L	L	L	L	1EH	X	XX 0000	00H
Read Device ID	5V	H	L	H	H	L	L	L	L	L	51H	X	XX 0001	00H
Read Device ID	5V	H	L	H	H	L	L	L	L	L	07H	X	XX 0010	00H

Notes:
1. Write Code Data requires a 200 ns $\overline{PROG}$ pulse.
2. Write Lock Bits requires a 100 µs $\overline{PROG}$ pulse.
3. Chip Erase requires a 200 ns - 500 ns $\overline{PROG}$ pulse.
4. RDY/$\overline{BSY}$ signal is output on P3.0 during programming.

Figure 22-1. Programming the Flash Memory

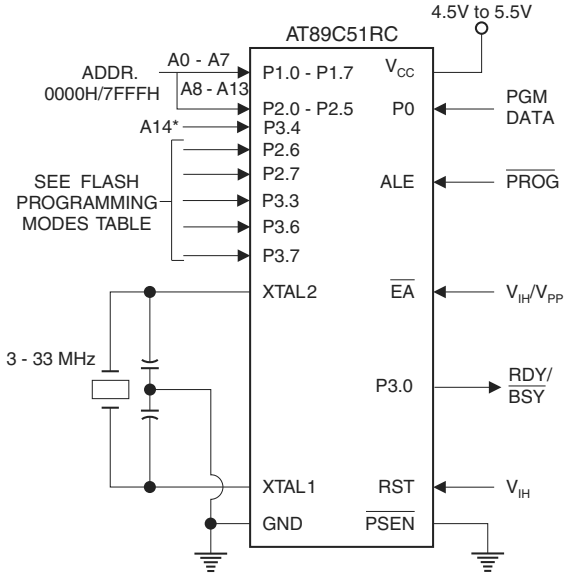
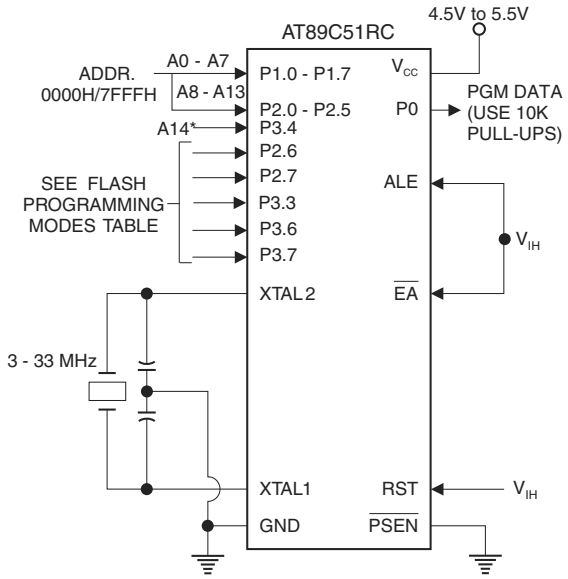
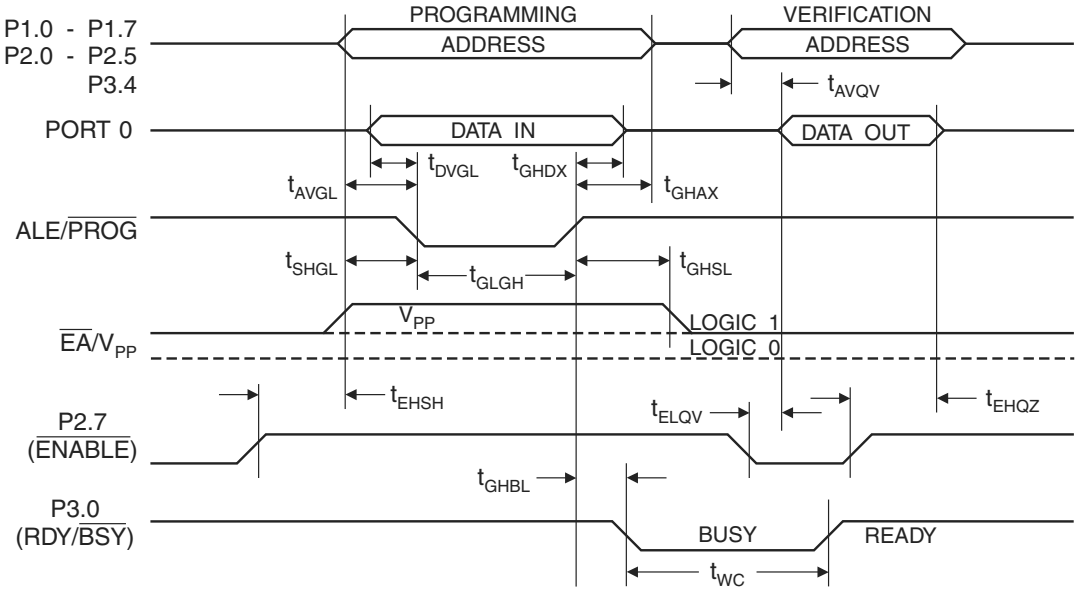


Figure 22-2. Verifying the Flash Memory

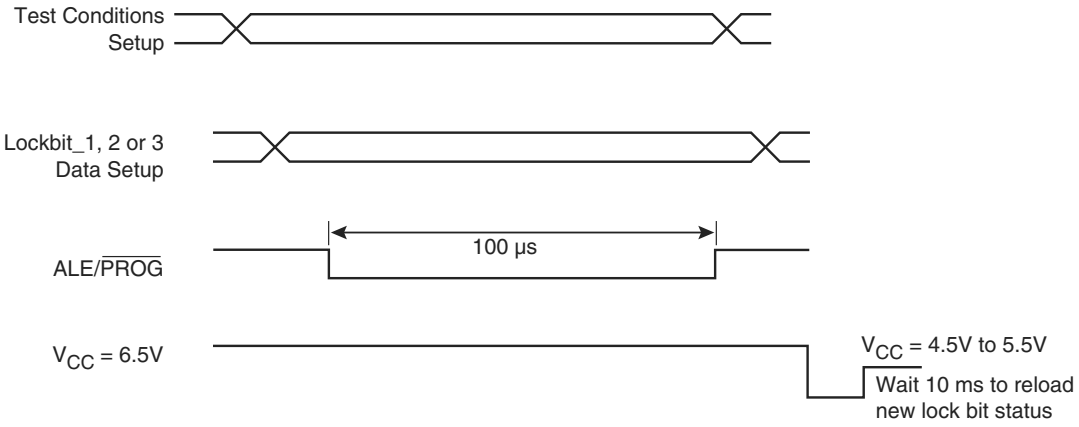


Note: *Programming address line A14 (P3.4) is not the same as the external memory address line A14 (P2.6).

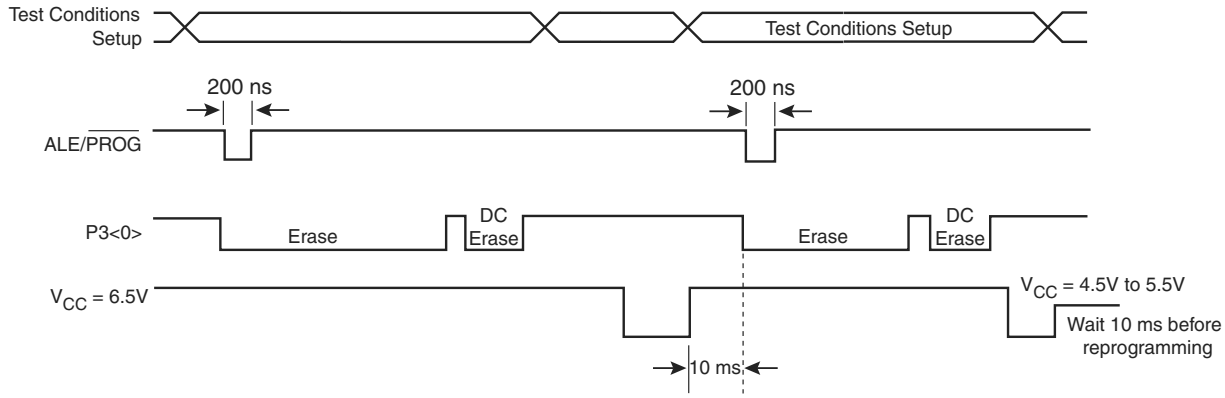
24. Flash Programming and Verification Waveforms



25. Lock Bit Programming



26. Parallel Chip Erase Mode



27. Absolute Maximum Ratings*

Operating Temperature	-55°C to +125°C
Storage Temperature	-65°C to +150°C
Voltage on Any Pin with Respect to Ground	-1.0V to +7.0V
Maximum Operating Voltage	6.6V
DC Output Current	15.0 mA

*NOTICE: Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

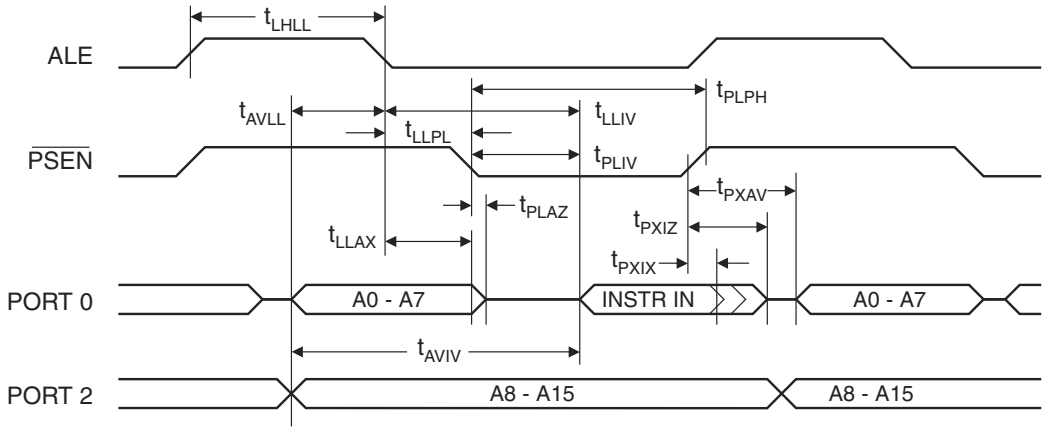
28. DC Characteristics

The values shown in this table are valid for T_A = -40°C to 85°C and V_{CC} = 4.0V to 5.5V, unless otherwise noted.

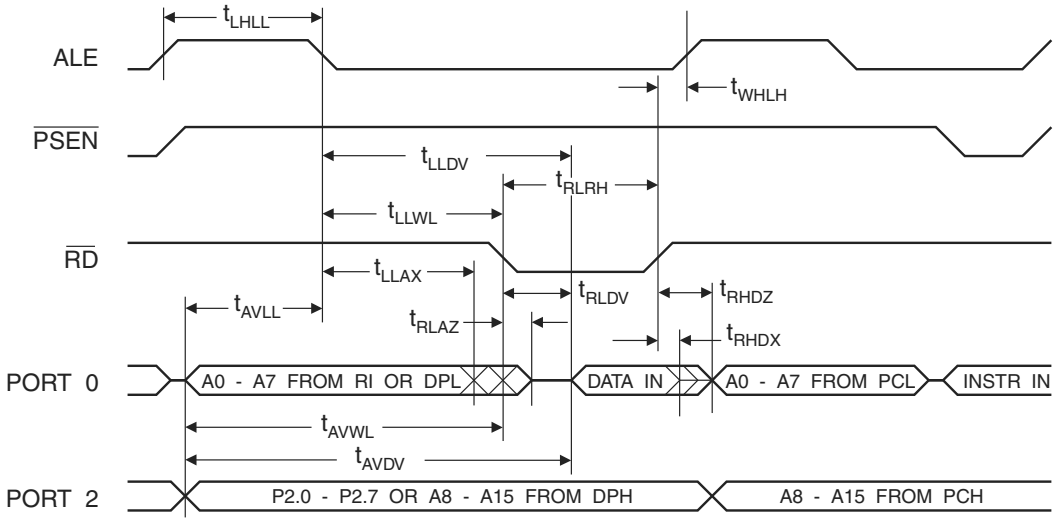
Symbol	Parameter	Condition	Min	Max	Units
V_{IL}	Input Low-voltage	(Except $\overline{EA}$)	-0.5	0.2 V_{CC}-0.1	V
V_{IL1}	Input Low-voltage ($\overline{EA}$)		-0.5	0.2 V_{CC}-0.3	V
V_{IH}	Input High-voltage	(Except XTAL1, RST)	0.2 V_{CC}+0.9	V_{CC}+0.5	V
V_{IH1}	Input High-voltage	(XTAL1, RST)	0.7 V_{CC}	V_{CC}+0.5	V
V_{OL}	Output Low-voltage(1) (Ports 1,2,3)	I_{OL} = 1.6 mA		0.45	V
V_{OL1}	Output Low-voltage(1) (Port 0, ALE, $\overline{PSEN}$)	I_{OL} = 3.2 mA		0.45	V
V_{OH}	Output High-voltage (Ports 1,2,3, ALE, $\overline{PSEN}$)	I_{OH} = -60 µA, V_{CC} = 5V ±10%	2.4		V
		I_{OH} = -25 µA	0.75 V_{CC}		V
		I_{OH} = -10 µA	0.9 V_{CC}		V
V_{OH1}	Output High-voltage (Port 0 in External Bus Mode)	I_{OH} = -800 µA, V_{CC} = 5V ±10%	2.4		V
		I_{OH} = -300 µA	0.75 V_{CC}		V
		I_{OH} = -80 µA	0.9 V_{CC}		V
I_{IL}	Logical 0 Input Current (Ports 1,2,3)	V_{IN} = 0.45V		-50	µA
I_{TL}	Logical 1 to 0 Transition Current (Ports 1,2,3)	V_{IN} = 2V, V_{CC} = 5V ±10%		-650	µA
I_{LI}	Input Leakage Current (Port 0, $\overline{EA}$)	0.45 < V_{IN} < V_{CC}		±10	µA
RRST	Reset Pull-down Resistor		10	30	kΩ
C_{IO}	Pin Capacitance	Test Freq. = 1 MHz, T_A = 25°C		10	pF
I_{CC}	Power Supply Current	Active Mode, 12 MHz		25	mA
		Idle Mode, 12 MHz		6.5	mA
	Power-down Mode(1)	V_{CC} = 5.5V		100	µA

Notes:
1. Under steady state (non-transient) conditions, I_{OL} must be externally limited as follows:
   Maximum I_{OL} per port pin: 10 mA
   Maximum I_{OL} per 8-bit port:
   Port 0: 26 mA Ports 1, 2, 3: 15 mA
   Maximum total I_{OL} for all output pins: 71 mA
   If I_{OL} exceeds the test condition, V_{OL} may exceed the related specification. Pins are not guaranteed to sink current greater than the listed test conditions.
2. Minimum V_{CC} for Power-down is 2V.

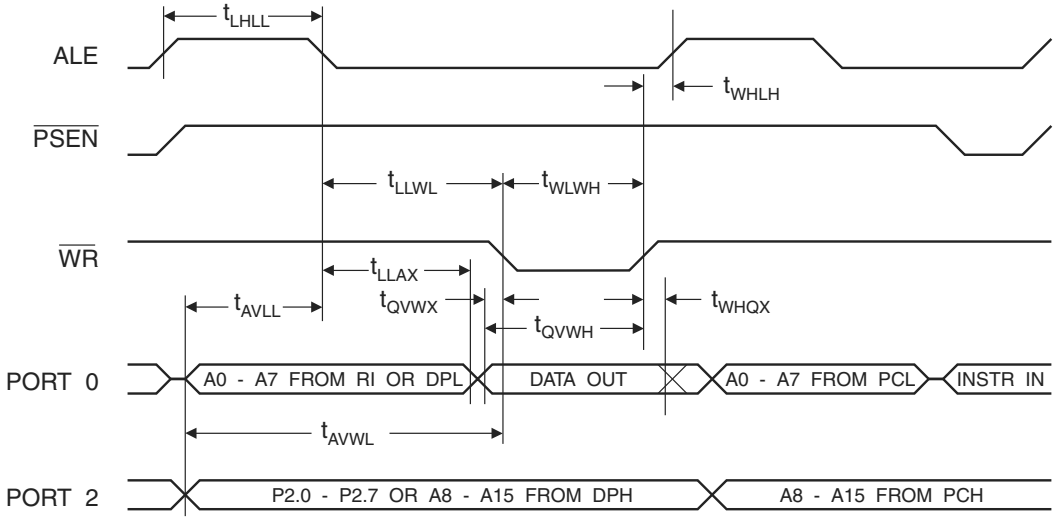
30. External Program Memory Read Cycle



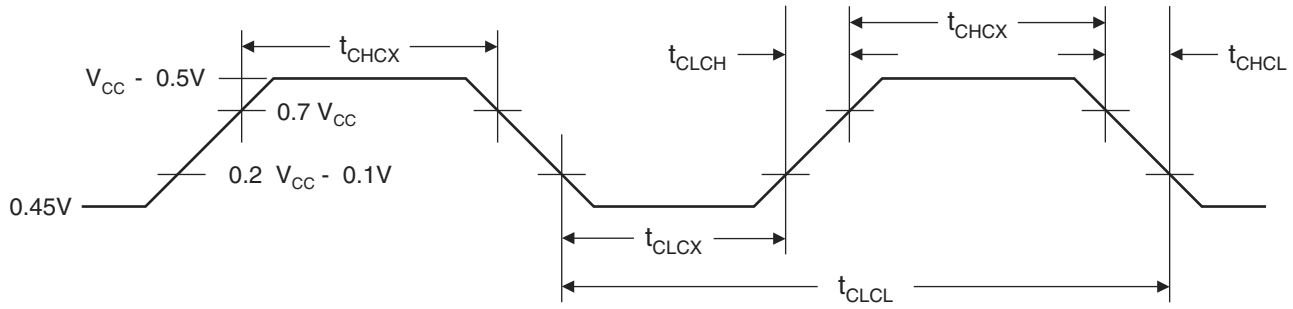
31. External Data Memory Read Cycle



32. External Data Memory Write Cycle



33. External Clock Drive Waveforms



34. External Clock Drive

Symbol	Parameter	Min	Max	Units
$1/t_{CLCL}$	Oscillator Frequency	0	33	MHz
t_{CLCL}	Clock Period	30		ns
t_{CHCX}	High Time	12		ns
t_{CLCX}	Low Time	12		ns
t_{CLCH}	Rise Time		5	ns
t_{CHCL}	Fall Time		5	ns

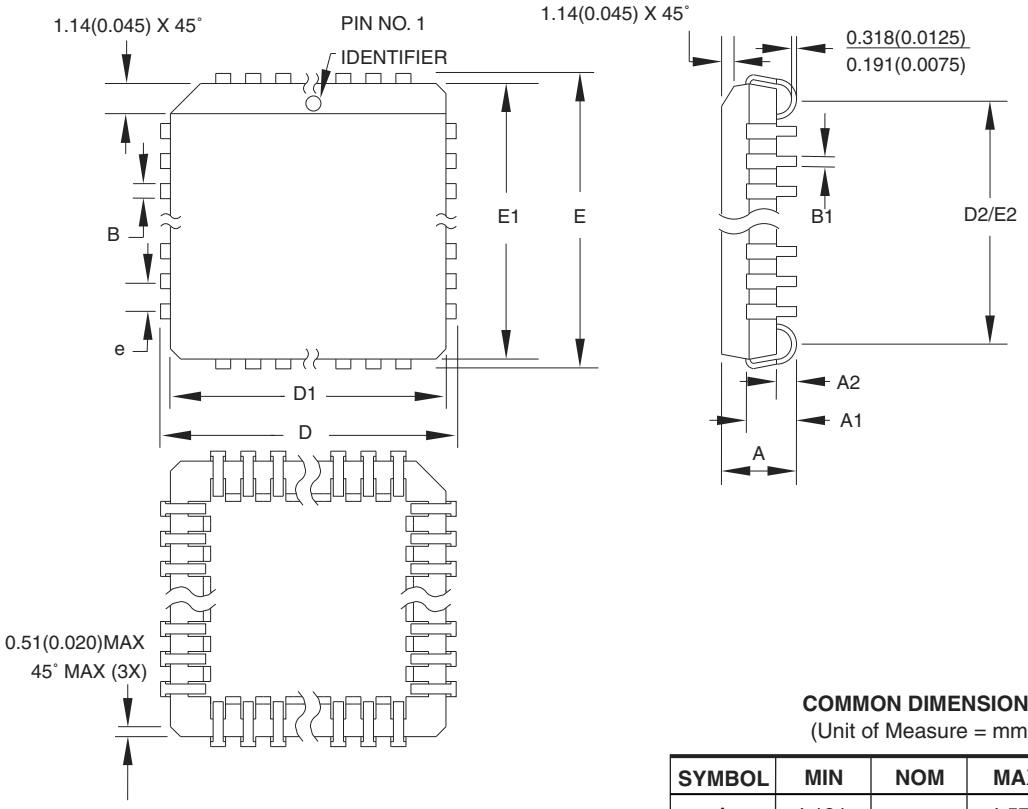
39. Ordering Information

39.1 Green Package Option (Pb/Halide-free)

Speed (MHz)	Power Supply	Ordering Code	Package	Operation Range
24	4.0V to 5.5V	AT89C51RC-24AU AT89C51RC-24JU AT89C51RC-24PU	44A 44J 40P6	Industrial (-40° C to 85° C)
33	4.5V to 5.5V	AT89C51RC-33AU AT89C51RC-33JU AT89C51RC-33PU	44A 44J 40P6	Industrial (-40° C to 85° C)

Package Type	
44A	44-lead, Thin Plastic Gull Wing Quad Flatpack (TQFP)
44J	44-lead, Plastic J-leaded Chip Carrier (PLCC)
40P6	40-lead, 0.600" Wide, Plastic Dual Inline Package (PDIP)

40.2 44J – PLCC



COMMON DIMENSIONS
(Unit of Measure = mm)

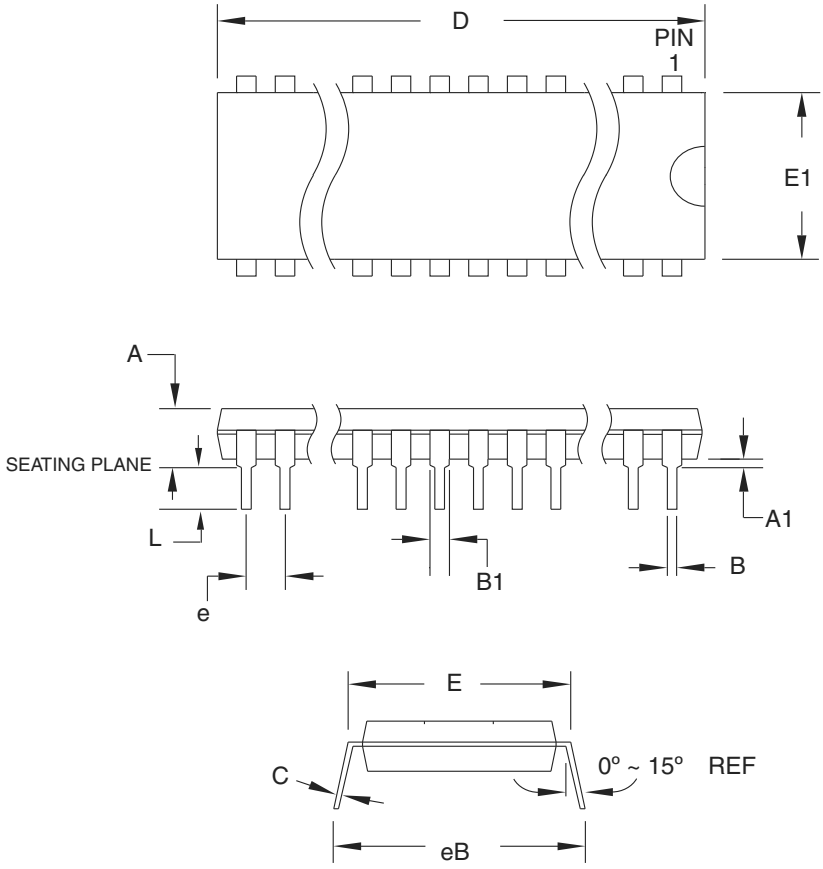
SYMBOL	MIN	NOM	MAX	NOTE
A	4.191	–	4.572	
A1	2.286	–	3.048	
A2	0.508	–	–	
D	17.399	–	17.653	
D1	16.510	–	16.662	Note 2
E	17.399	–	17.653	
E1	16.510	–	16.662	Note 2
D2/E2	14.986	–	16.002	
B	0.660	–	0.813	
B1	0.330	–	0.533	
e	1.270 TYP			

Notes:
1. This package conforms to JEDEC reference MS-018, Variation AC.
2. Dimensions D1 and E1 do not include mold protrusion. Allowable protrusion is .010"(0.254 mm) per side. Dimension D1 and E1 include mold mismatch and are measured at the extreme material condition at the upper or lower parting line.
3. Lead coplanarity is 0.004" (0.102 mm) maximum.

10/04/01

	TITLE	DRAWING NO.	REV.
2325 Orchard Parkway San Jose, CA 95131	**44J**, 44-lead, Plastic J-leaded Chip Carrier (PLCC)	44J	B

40.3 40P6 – PDIP



COMMON DIMENSIONS
(Unit of Measure = mm)

SYMBOL	MIN	NOM	MAX	NOTE
A	–	–	4.826	
A1	0.381	–	–	
D	52.070	–	52.578	Note 2
E	15.240	–	15.875	
E1	13.462	–	13.970	Note 2
B	0.356	–	0.559	
B1	1.041	–	1.651	
L	3.048	–	3.556	
C	0.203	–	0.381	
eB	15.494	–	17.526	
e	2.540 TYP			

Notes: 1. This package conforms to JEDEC reference MS-011, Variation AC.
2. Dimensions D and E1 do not include mold Flash or Protrusion. Mold Flash or Protrusion shall not exceed 0.25 mm (0.010").

09/28/01

	TITLE	DRAWING NO.	REV.
2325 Orchard Parkway San Jose, CA 95131	**40P6**, 40-lead (0.600"/15.24 mm Wide) Plastic Dual Inline Package (PDIP)	40P6	B